

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all previous versions and listings of claims in this application.

Claim Listing:

1. (Canceled).

2. (Currently amended) ~~The method of soldering a semiconductor part according to claim 1, A method of soldering a semiconductor part, the method comprising:~~

~~printing a cream solder on a land on a circuit substrate;~~

~~mounting a semiconductor part in which a metal terminal is formed on a back surface and a side surface on said cream solder so that only a back surface portion of said metal terminal is in contact with said cream solder; and~~

~~performing solder joining of said land and said semiconductor part by irradiating only a side surface portion of said metal terminal with laser beams,~~

wherein in said step of performing solder joining, cold air is supplied to a surface of said semiconductor part on which said metal terminal is not formed.

3. (Currently amended) ~~The method of soldering a semiconductor part according to claim 2, A method of soldering a semiconductor part, the method comprising:~~

~~printing a cream solder on a land on a circuit substrate;~~

~~mounting a semiconductor part in which a metal terminal is formed on a back surface and a side surface on said cream solder so that only a back surface portion of said metal terminal is in contact with said cream solder; and~~

performing solder joining of said land and said semiconductor part by irradiating only a side surface portion of said metal terminal with laser beams,

wherein temperature conditions are set so that a difference between a temperature near said metal terminal which is irradiated with said laser beams and a temperature near the surface to which said cold air is supplied becomes within a prescribed temperature.

Claims 4-6: (Canceled).

7. (Currently amended) The method of claim 6, further comprising A method of soldering a heat sensitive semiconductor part incapable of being passed through a reflow furnace to a circuit substrate, the method comprising:

printing a cream solder on a land on the circuit substrate;

providing a heat sensitive semiconductor part incapable of being passed through a reflow furnace, wherein the semiconductor part has a metal terminal formed on both a back surface portion and a side surface portion of the semiconductor part;

mounting the back surface portion of the metal terminal on said cream solder so that only the back surface portion of said metal terminal is in contact with said cream solder;

irradiating only the side surface portion of the metal terminal with a laser beam;

solder joining the land and said semiconductor part together; and

supplying cold air to a top surface of the heat sensitive semiconductor part on which the metal terminal is not formed and protecting the heat sensitive semiconductor part from a soldering heat-induced failure.

8. (Currently amended) The method of claim 7, further comprising A method of soldering a heat sensitive semiconductor part incapable of being passed through a reflow furnace to a circuit substrate, the method comprising:

printing a cream solder on a land on the circuit substrate;

providing a heat sensitive semiconductor part incapable of being passed through a reflow furnace, wherein the semiconductor part has a metal terminal formed on both a back surface portion and a side surface portion of the semiconductor part;

mounting the back surface portion of the metal terminal on said cream solder so that only the back surface portion of said metal terminal is in contact with said cream solder;

irradiating only the side surface portion of the metal terminal with a laser beam;

solder joining the land and said semiconductor part together; and

maintaining a temperature difference between the top surface of the semiconductor part and the side surface portion of the metal terminal in a prescribed range.

Claims 9-11: (Canceled).